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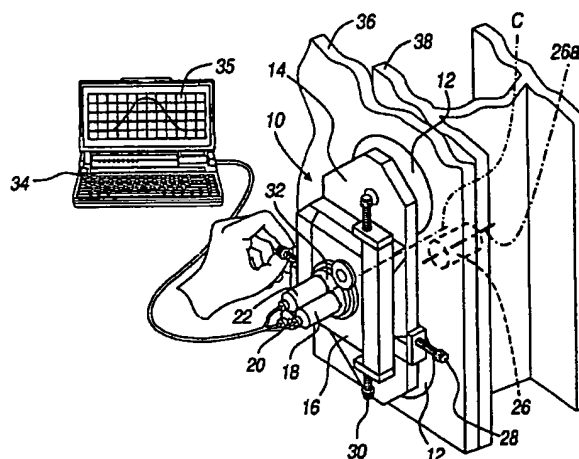
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(54) Title: **MAGNETIC INDEXER FOR HIGH ACCURACY HOLE DRILLING**



(57) Abstract: A magnetic indexer (10) for locating a device (26) producing a magnetic field in a blind or inaccessible position of a work piece (36). A magnet (26) is initially placed on a first side of the work piece (36) such that a magnetic field produced by the magnet extends through the work piece (36) and substantially perpendicular to a surface of the work piece (36). A device comprising a plurality of probes (18, 20, 22) for sensing magnetic fields is then positioned over a second surface of the work piece (36). The probes (18, 20, 22) are then moved over the second surface to determine the location of the axis (26a) of the magnet (26) via the strength of the sensed magnetic field. Once the position of the axis (26a) of the magnet (26) is determined, the work surface is either marked or worked on through the platform on which the probes (18, 20, 22) are positioned. In particular, a hole may be accurately drilled or otherwise formed directly over the magnet (26) even when the first surface of the work piece (26) cannot be seen. Additionally, the present invention allows a very accurate positioning of a work tool on the second surface without the need to first visualize the first surface of the work piece (36).

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MAGNETIC INDEXER FOR HIGH ACCURACY HOLE DRILLING

FIELD OF THE INVENTION

[0001] The present invention relates to a system to precisely form
5 holes, and more particularly to a system to locate a device and indicate a location to form a hole.

BACKGROUND OF THE INVENTION

[0002] It is often desirable to locate, with a high degree of accuracy
10 and specificity, locations in a blind area of a working surface. In particular, if it is desired to affix together two portions of a structure, where only an outside surface is visible to a work person, it is often difficult, if not impossible, to precisely and reproducibly place a fastener between the two portions. This is particularly relevant in regards to aircraft where the skin of the aircraft is
15 placed over an internal frame structure and must be affixed thereto. Once the skin is in place, it is often very difficult to properly locate a fastener that must first go through the skin to be affixed to the internal structure of the aircraft. This situation arises in other construction and manufacturing instances as well.

[0003] One solution has been the attempt to back drill from inside
20 the structure. That is, to have a work person physically place themselves inside the structure and then cut through the sub-structure through the skin. This, however, often creates impreciseness in the hole creation. For example, the full sized hole which is formed normal to the skin of the air craft, which is following the back drilled pilot hole, may be angular. That is because
25 the hole formed from the inside of the skin can not be easily formed exactly normal to the skin of the aircraft. In particular the internal structures of the part may not be normal to the skin while the hole on through the outside of the skin must be normal to the skin. Furthermore, it is very hard on the work
30 person who must crawl into the usually small areas to produce the holes.

[0004] Backmarkers are widely used in the aircraft industry to transfer holes from the understructure to the outside surface. Backmarkers

consist of a long split piece of thin metal with a pin on one side and a hole on the other that are in alignment. The pin side is slipped under the skin to line up with a pilot hole, in the understructure, and a pilot hole is drilled into the outer skin. This method does not work on wide parts and thick parts.

- 5 Deflection of the split plates and the difficulty of installing the device on thick parts limits the use to thin sheet metal areas near the edge of the skin.

[0005] Another method is to use a probe or locating device to determine a precise position on the skin. In particular, the device is first programmed with locations in three dimensional space. Therefore, when a
10 surface is placed within reach of the probe, the probe can determine the location of a point which the probe touches. This, however, requires an extensive pre-programming and precise placement of the surface which is to be probed. Using such special orientation probes increases time and manufacturing costs for many applications. Also, probing the understructure
15 before drilling has several shortcomings. When a skin is placed over a built up structure, the weight of the skin causes the structure and tooling to deform. It is possible that probed holes will move between measurements and drilling. Also, temperature changes between probing and drilling can cause the holes to not align due to growth or shrinkage to the part and differences in growth
20 between the upper and lower surfaces. Fastener induced growth and coldworking of holes in aircraft structure can also shift positions of the holes between probing and drilling.

[0006] In aircraft construction, it is often critical to produce a hole, for fastening a portion of the airframe to another portion, within hundredths of
25 an inch. One specific method of construction for internal airframe structure involves the use of sine wave topography on the internal structures or beams of the aircraft. To ensure a sufficiently strong connection, which will withstand the extreme stresses that an aircraft will encounter, the fastener must be placed at a peak of the sine wave. Therefore, placement of a fastener must
30 be extremely precise to ensure that a peak is hit, rather than a valley or a portion adjacent to the peak. It is also desirable to precisely locate edges of

hidden structure pieces. In this and many other applications, the precise locating of the fastener becomes critically important.

SUMMARY OF THE INVENTION

5 **[0007]** The present invention is directed to a magnetic indexer which locates a device that is producing a magnetic field in a blind or inaccessible position. A magnet is initially placed on one side of the work surface such that a magnetic field produced by the magnet extends through the work surface such that the axis of the magnetic field is substantially
10 perpendicular to the work surface. The device, comprising a plurality of probes which are affected by magnetic fields, is positioned over the opposite side of the work surface. The probes are then moved over the work surface to determine the location of the magnet. Once the position of the magnetic field axis is determined, the work surface is either marked or worked on
15 through the platform on which the probes are positioned. In particular, a hole may be reproducibly placed directly over the magnet even when the underside of the work piece is not visible. Additionally, with the present invention, a work tool may be very accurately positioned on the work surface without seeing the underside of the work surface.

20 **[0008]** A first embodiment of the present invention includes a system for determining a location of a device that produces a field having varying strengths depending upon a lateral distance from the device. The system comprises a probe adapted to be affected by the varying strength of the field produced by the device and which assists in locating the device. As
25 the probe is moved a processor determines the field strength affecting the probe. A confirmation system provides a physical confirmation that the processor has determined the location of the device with the probe.

[0009] A second embodiment of the present invention includes a system to determine a location of a device through a surface. The system
30 comprises a device, which produces a magnetic field, positioned on a first side of the surface. A probe is positioned on a second side of the surface affected by the field. A processor determines the affect produced in the

probe by the field. The processor is adapted to determine the position of the device based upon the affect of the field on the probe.

5 **[0010]** The present invention also provides a new method to precisely locate a position. The method involves locating a device, which produces a field, with a probe affected by the field. The device is placed on a first side of a surface. A field is then produced with the device through the surface. A probe is used on a second side of the surface to determine a center axis of the field and to provide a physical confirmation of the center axis of the field. Once the location of the center axis of the field is determined
10 then work may be performed at a precise and predetermined location.

[0011] Further areas of applicability of the present invention will become apparent from the detailed description provided hereinafter. It should be understood that the detailed description and specific examples, while indicating the preferred embodiment of the invention, are intended for
15 purposes of illustration only and are not intended to limit the scope of the invention.

BRIEF DESCRIPTION OF THE DRAWINGS

[0012] The present invention will become more fully understood
20 from the detailed description and the accompanying drawings, wherein:

[0013] Figure 1 is a perspective view of a preferred embodiment of the digital magnetizer according to the present invention;

[0014] Figure 2 is a side elevational view of the magnetic indexer according to the present invention;

25 **[0015]** Figure 3 is a perspective view of the magnetic indexer in use;

[0016] Figure 4 is a perspective view of the platform of the magnetic indexer after it has been positioned;

[0017] Figure 5 is a perspective view of a magnetic indexer according to a second embodiment of the present invention; and

30 **[0018]** Figure 6 is a perspective view of a third embodiment of the magnetic indexer affixed to a robot.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0019] The following description of the preferred embodiment(s) is merely exemplary in nature and is in no way intended to limit the invention, its application, or uses.

5 **[0020]** With reference to Figures 1 and 2, a magnetic indexer 10 in accordance with a preferred embodiment of the present invention is shown. The magnetic indexer 10 includes a vacuum attachment member 12, a work piece platform 14, a probe platform 16 and a plurality of probes 18, 20, and 22. The vacuum attachment member 12 generally includes members in
10 which a vacuum may be created, so as to affix the work piece platform 14 to a work piece (described further herein). It will be understood, however, that any appropriate system suitable for attaching the work piece platform 14 to a work piece may be used. Extending generally perpendicular from the work piece platform 14 are stabilizing members 24 (Figure 2) which engage the work
15 piece to ensure that the work piece platform 14 is substantially parallel to the work piece. A magnet 26 is positioned on an opposite side of the work piece from the work piece platform 14. The magnet 26 produces a magnetic field which has a central magnetic axis 26a. Extending from the work piece platform 14 is the probe platform 16. The probe platform 16 is moveable
20 relative to the work piece platform 14. A first set of adjustment screws 28 allow for movement of the probe platform 16 in a first axis A. A second set of adjustment screws 30 allow for adjustment of the probe platform 16 along a second axis B. Therefore the probe platform 16 may be moved, relative to the work piece platform 14, using the first set of adjustment screws 28 and the
25 second set of adjustment screws 30, in two dimensions.

[0021] Affixed to the probe platform 16 are probes 18, 20 and 22. The probes 18, 20 and 22 are spaced apart so that the probes define a center axis C. The center axis C is an axis equidistant from, but parallel to, an axis along which each of the probes 18, 20 and 22 extend.

30 **[0022]** The probes 18, 20, 22 are affixed to a secondary probe platform 32 which is affixed to the probe platform 16 with a fastener 33. This

allows the secondary probe platform 32 to be removed from the probe platform 16 without moving the work piece platform 14.

[0023] With reference to Figures 3 and 4, the effect of each probe 18, 20, 22 is determined by a processor 34. The processor 34 may be any appropriate processor, however, a microprocessor is able to determine the effect of the magnetic field on each of the probes 18, 20, 22 and to determine the relative orientation of each of the probes 18, 20, and 22 to the magnetic field. The processor's 34 determination is displayed on a display device 35. In particular, a CRT or LCD screen may be used as the display device 35. The processor 34 can display on the display device 35 a confirmation that the center axis C is co-linear with the magnetic axis 26a

[0024] The magnetic indexer 10 is affixed to a surface or work piece 36 with the vacuum attachment members 12. As discussed above, the vacuum attachment members 12 may affix the work piece platform 14 to the work piece 36 through any appropriate means. For example, a vacuum may be created within the vacuum attachment members 12 allowing the work piece platform 14 to be held in place. It will also be understood that more than two vacuum attachment members 12 may be used depending upon the size of the work piece platform 14.

[0025] Below the work piece 36 is a sub-structure or support beam 38. At the position where a hole must be produced, a magnet 26 has been placed. The magnet 26 is placed on the beam 38 in a preliminary manufacturing step before the work piece platform 14 is secured to the work piece 36. Because of this, the magnet 26 is able to be easily placed in the exact position where a hole must be produced for an attachment between the work piece 36 and the beam 38. The magnetic indexer 10 is placed over a position relatively close to where the hole must be produced. Then, using the adjustment screws 28, 30, the probe platform 16 is adjusted until the center axis C is directly over or co-linear with the magnetic axis 26a (through a process described more fully herein).

[0026] Once the center axis C is aligned directly over the magnetic axis 26a, the secondary probe platform 32 is removed so that a drill bit 40

may drill through the probe platform 16 and work piece platform 14 to produce a hole in the work piece 36. It will be understood that additional drill guide members may be put in place of the secondary probe platform 32 to increase the precision of the drilling step performed by the drill bit 40 as it proceeds
5 through the magnetic indexer 10.

[0027] Once the hole is produced through the work piece 36 and the beam 38, the magnet 26 is removed during a clean up process of the internal area. Furthermore, the magnetic indexer 10 is then removed from the work piece 36 by pressurizing the vacuum attachment members 12 to remove the
10 magnetic indexer 10 from the work piece 36. Then, any appropriate fastener is used to affix the work piece 36 permanently to the beam 38.

[0028] The exact location of the magnet 26 is determined by locating the magnetic axis 26a which is a north-south (N-S) pole axis of the magnet 26. The magnetic axis 26a, also termed the center or field axis, of the
15 magnet 26 is the center of the magnetic field and the area where the magnetic field is the strongest. The magnet 26 is placed on the beam 38 so that the magnetic axis 26a is substantially perpendicular to the surface of the beam 38. Therefore, once the work piece 36 is affixed to the beam 38, the magnetic axis 26a is also perpendicular to the surface of the work piece 36.
20 Additionally, the work piece 36 should not interfere with the magnetic field produced by the magnet 26. It will be understood, however, that as long as the magnetic field of the magnet 26 is powerful enough for the probes 18, 20, 22 to sense the field produced by the magnet 26, the work piece 36 may be formed of virtually any non-magnetic material.

[0029] It will be understood that a reference to a single probe 18 in
25 the following description is exemplary of each of the probes 18, 20, 22 and its description as a single probe is merely for clarity. The probe 18 is affected by, that is the probe 18 senses, the magnetic field produced by the magnet 26. One exemplary probe type is a Hall-Effect probe. In the Hall-Effect probe 18,
30 the magnetic field produced by the magnet 26 creates a voltage when a current is running perpendicular to the field in the Hall-Effect probe 18. The Hall-Effect probe 18 measures the induced voltage produced due to the

magnetic field of the magnet 26. Knowing the induced voltage, and the current, the strength of the magnetic field is determined using the equation $V_H n e d / I = B$. According to the equation, V_H is equal to the Hall-voltage, n is equal to the charge carrier density, e is equal to the electronic charge, d is equal to the strip width, and I is equal to the current. This equation results in B which is the strength of magnetic field. Once the strength of the magnetic field is known by use of the Hall-Effect probe 18, the location of the magnetic axis 26a may be determined. The closer the Hall-Effect probe 18 is to the magnetic axis 26a, the greater the response in the Hall-Effect probe 18.

10 According to the first embodiment, the magnetic axis 26a is located co-linear with the center axis C of the probes 18, 20, and 22 when the response by each of the probes 18, 20, and 22 is substantially equal.

[0030] The processor 34 determines and processes the affect produced on each of the probes 18, 20, and 22. The display device 35 displays the affect determined by the processor 34. The processor 34 may also indicate which way the probe platform 16 should be moved, using the adjustment screws 28, 30, to correctly position the center axis C over the magnetic axis 26a. Then, once each of the probes 18, 20, 22 indicates an equivalent response, it is known that the center axis C is positioned directly over the magnetic axis 26a. At this point, the display indicates that the center axis C is over the magnetic axis 26a and that the operator should make no further adjustments. In particular, the center axis C is co-linear with the magnetic axis 26a of the magnet 26. Once it is displayed that the center axis C is over the magnetic axis 26a, the secondary probe platform 32 is removed so that the drill point or bit 40 may be introduced to produce the desired hole.

[0031] With reference to Figure 5, a second embodiment of a magnetic indexer system 50 includes a moveable sensor canister 52 with directional or signaling LEDs 54, 56, 58 and 60 affixed to the top of the moveable canister 52. Each LED 54, 56, 58, and 60 may include an array of LEDs such that a strength of the response in a particular direction can be indicated. Placed centrally and along a center axis D is a marker 62 which extends through the moveable canister 52 to selectively engage the work

piece 36. The center axis D relates to probes 64, 66 and 68 as center axis C relates to probes 18, 20, 22 according to the first embodiment.

[0032] Each of the probes 64, 66 and 68 are connected to a processor 70. The probes 64, 66 and 68 work substantially similarly to the probes 18, 20 and 22 described in reference to the first embodiment. The processor 70 also works similar to the processor 34 discussed above. In the magnetic indexer 50, however, the processor 70 determines the location of the center axis D relative to the magnetic axis 26a and illuminates the appropriate LED 54, 56, 58 and 60 indicating the direction the moveable canister 52 must be moved to properly align the center axis D with the magnetic axis 26a. Once the center axis D is placed substantially co-linear with the magnetic axis 26a of the magnet 26, all four LED arrays 54, 56, 58 and 60 illuminate to show that the center axis D is properly aligned over the magnetic axis 26a. That is, when all four LEDs 54, 56, 58, 60 are illuminated, they create a visual confirmation that the magnetic axis 26a is positioned substantially co-linear with the center axis D. At this point, the marker 62 may be depressed to form a mark at the position on the work piece 36.

[0033] Once the mark has been made, the moveable canister 52 is simply removed from the work piece 36 and proper chucks may be affixed to the work piece 36 to ensure that a properly aligned hole is produced in the work piece 36. Again, once the hole is formed through the work piece 36 and the beam 38, the magnet 26 and any debris may be cleaned out of the internal space.

[0034] With reference to Figure 6, a third embodiment of a magnetic indexer 80 is illustrated. The magnetic indexer 80 includes a single probe 82 which is affixed to an arm 84 of a robot 86. It will be understood that a plurality of probes can also be used with the robot 86. Only one probe 82, however, is necessary if placed next to the surface 88 in one location and then moved to another location along the surface 88 with an exact knowledge of the first location. Therefore, an effective plurality of probes is simulated by simply placing and moving the single probe 82 and exactly recalling the

previous placements, and the field measurements, for each of the previous placements.

[0035] A magnet 90, which produces a magnetic field having a central magnetic axis 90a, is placed near the surface 88 opposite the magnetic indexer 80. A processor 94 determines the response of the probe 82 and controls the robot 86. In this way, the robot 86 can quickly locate the magnetic axis 90a, of the magnet 90, affixed to the support sheet 92. It will be understood, however, that separate processors may be used to determine the location of the magnetic axis 90a and control the robot 86. In addition, once the processor 94 has determined the exact location of the magnetic axis 90a, a tool may be placed on the robot arm 84 to produce the hole required. It will also be understood that a plurality of arms may extend from the robot 86 so that once the position of the magnetic axis 90a is located, a tool arm simply rotates in place with a tool extending from the tool arm to produce the hole in the surface 88. When a robot 86 is used, producing a hole serves to confirm that the magnet 90 has been properly located.

[0036] It will be understood that each embodiment of the present invention does not require a Hall-Effect probe. Any probe which is sensitive to or which can detect the magnetic field produced by the magnet 26, 90 may be used in the present invention. One alternative probe is a Three-Axis Magnetic Sensor Hybrid HMC2003 produced by Solid State Electronics Center, a division of Honeywell. The other portions of the magnetic indexer 10 are reproduced while simply replacing the Hall-Effect probe 18 with the alternative probe. If the alternative probe, such as the HMC2003, is able to determine a magnetic axis in more than one relative axis, then only one probe may be necessary on the magnetic indexer 10. It is still understood, however, that the single alternative probe still defines a central probe axis for determining the magnetic axis 26a, 90a. The alternative probe is still able to detect the field produced by the magnet 26, 90 and is able to indicate the magnetic axis 26a, 90a.

[0037] It will also be understood that the magnet used in the present invention must have their magnetic axis 26a, 90a properly and precisely

aligned. Therefore, it may be desirable to first test the magnet 26, 90 using the magnetic indexer 10 to ensure that the magnetic axis 26a, 90a is properly aligned so that when the magnet 26, 90 is affixed to the beam 38 or the support sheet 92, the magnetic axis 26a, 90a is substantially perpendicular to the surface of the work piece 36, 88. This is because only when the magnetic axis 26a, 90a is produced substantially perpendicular to the surface is the strength of the field weakened sequentially as one moves away from the magnetic axis 26a, 90a. It is the magnetic field acting upon the probes which is sensed by the probes 18, 20, 22; 64, 66, 68; and 82, which are used to determine where the magnets 26, 90 are positioned. If the magnetic axis 26a, 90a is angled to the surface (i.e., not perpendicular), the magnetic field would also not be perpendicular and the precise location of the magnetic axis 26a, 90a could not be correctly determined.

[0038] In addition, the magnetic indexer itself can be calibrated or zeroed. This means that the central axis of the magnetic indexer can be precisely determined before performing any tasks with the indexer. Generally, a magnetic source having a known magnetic axis can be placed at a zeroed position relative to the magnetic indexer, so that the magnetic indexer can be zeroed to that magnetic axis. After this, the precise zeroed position of the magnetic indexer is known and even greater preciseness can be attained with the magnetic indexer to locate a magnetic axis.

[0039] The preferred embodiments of the present invention thus provide a means to quickly and precisely detect the locations where holes need to be drilled in a work piece based on previously made hole location determinations that are otherwise not visible to an operator or optical detection machine. The preferred embodiments also allow for the precise detection of any non-visible landmark as well. That is, the present invention may be used to determine edges of hidden pieces as well. The present invention is especially well suited for aircraft manufacturing applications, but it will be appreciated that the invention will find utility in a wide variety of other manufacturing applications as well.

[0040] The description of the invention is merely exemplary in nature and, thus, variations that do not depart from the gist of the invention are intended to be within the scope of the invention. Such variations are not to be regarded as a departure from the spirit and scope of the invention.

CLAIMS

What is claimed is:

1. A system for determining a location of a device that produces a
5 magnetic field having a magnetic axis and varying strengths depending upon
a lateral distance from the device, the system comprising:
a probe adapted to be affected by the strength of the field
produced by the device to assist in locating the device;
a processor to determine the field strength affecting said probe;
10 and
a confirmation system to provide a physical confirmation that
said processor has determined the location of the magnetic axis with said
probe.
- 15 2. The system of claim 1, wherein the field produced by the device
is a magnetic field and said probe senses the magnetic field to determine the
strength of the magnetic field, such that an output of said probe indicates
when said probe is positioned closer to the magnetic axis.
- 20 3. The system of claim 2, wherein said processor determines the
magnetic field sensed by said probe.
4. The system of claim 1, wherein a plurality of said probes are
included and spaced apart about a center axis, wherein each of said probes is
25 affected by the field substantially simultaneously.
5. The system of claim 4, wherein said plurality of probes are
spaced equidistantly and wherein a center of the field is located substantially
collinear with the magnetic axis when each of said probes is affected
30 substantially equally by the field; and
wherein said processor determines when each of said probes is
affected substantially equally by the field.

6. The system of claim 5, wherein said confirmation system produces a display which confirms said center axis being substantially collinear with the magnetic axis.

5

7. The system of claim 6, wherein said display comprises a light emitted by a light-emitting-diode or a graphical display.

8. The system of claim 1, further comprising:
10 a robot;
a control system for said robot; and
wherein said probe is movable by said robot and said control system moves said probe via said robot until said processor has determined the location of the device.

9. A system to determine a location of a device through a surface of a work piece, the system comprising:

a magnet positioned on a first side of the work piece;

a magnetic field, produced by said magnet, comprising a
5 magnetic axis, where said magnetic axis is substantially perpendicular to a first surface of the work piece;

a probe positioned on a surface of the work piece, wherein the probe is affected by said magnetic field;

a processor to determine the affect produced in said probe by
10 said magnetic field;

wherein said probe defines a center axis;

wherein said affect on said probe is greatest when said center axis is substantially collinear with said magnetic axis;

wherein said processor is adapted to determine the position of
15 said magnet by sensing the affect of said magnetic field on said probe; and
wherein said processor produces a signal when said center axis is substantially collinear with said magnetic axis.

10. The system of claim 9, further comprising:

20 a platform;

wherein said probe comprises a plurality of probes spaced apart and affixed to said platform; and

wherein said plurality of probes defines a center axis.

25 11. The system of claim 10, wherein said affect on said plurality of probes is substantially equivalent when said center axis is substantially collinear with said magnetic axis.

30 12. The system of claim 9, further comprising a display device, wherein said signal produces a physical confirmation of said signal.

13. The system of claim 9, further comprising a confirmation system to produce a physical confirmation of the location of said magnetic axis.

14. A method locating a device, which produces a field, with a probe affected by the field, the method comprising:

- placing a device on a first side of a work piece;
- producing a field with said device through said work piece;
- 5 placing a probe adjacent a second side of said work piece;
- determining a location of a center field axis of said field with said probe; and
- providing a physical confirmation of said center field axis to a user.

10

15. The method of claim 14, wherein said step of placing a device comprises placing a magnet against said first side of said work piece, and wherein said field comprises a magnetic field which is adapted to produce a response in said probe.

15

16. The method of claim 14, wherein providing a probe comprises: providing at least three probes spaced apart defining a center probe axis;

- fixing said probes in a movable platform so that said center
- 20 probe axis is movable; and
- movably affixing said platform to said second side of said work piece.

17. The method of claim 16, wherein determining a location of said

25 center field axis comprises:

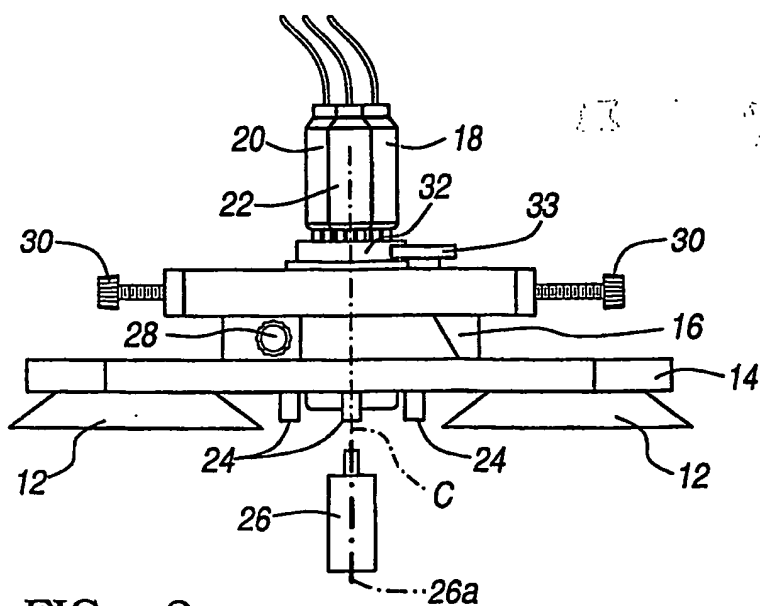
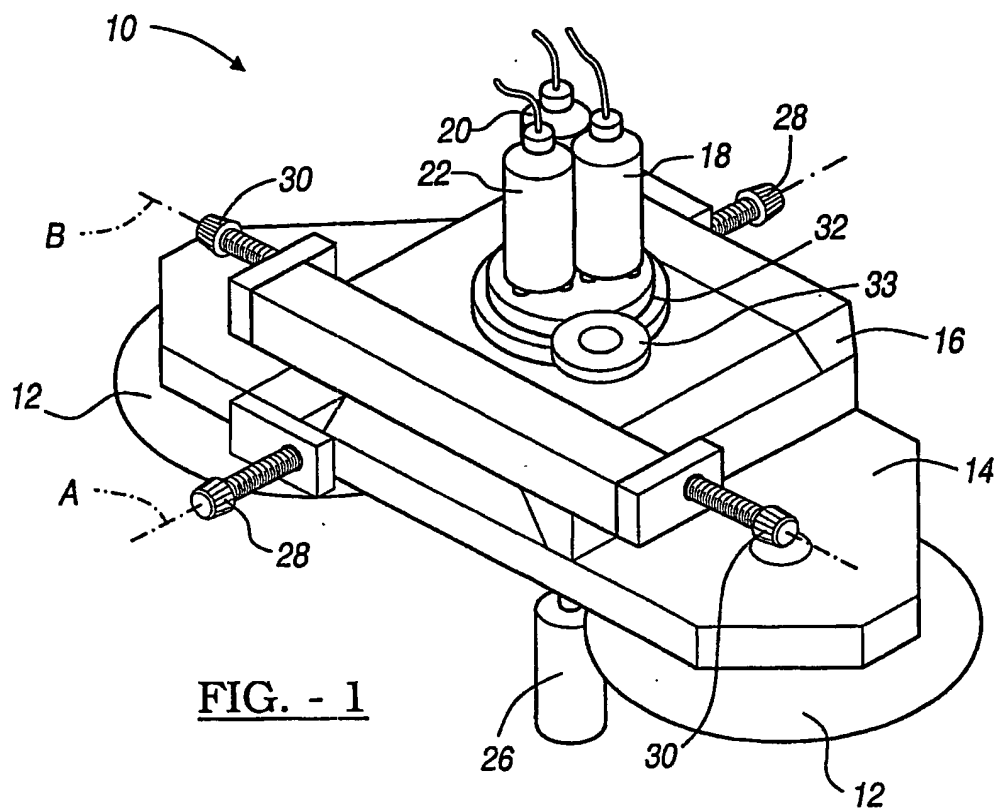
- moving said platform relative to a point on said second side of said surface;
- using said probes to sense the field as said probes are moved over said surface; and
- 30 providing a processor to determine the affect on said probes, wherein said processor determines when said center probe axis is collinear with the center field axis.

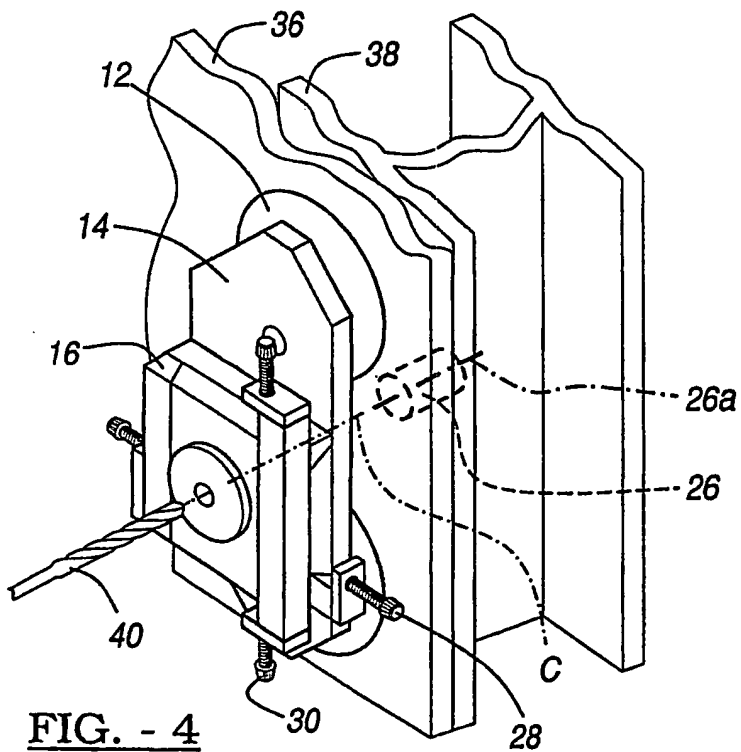
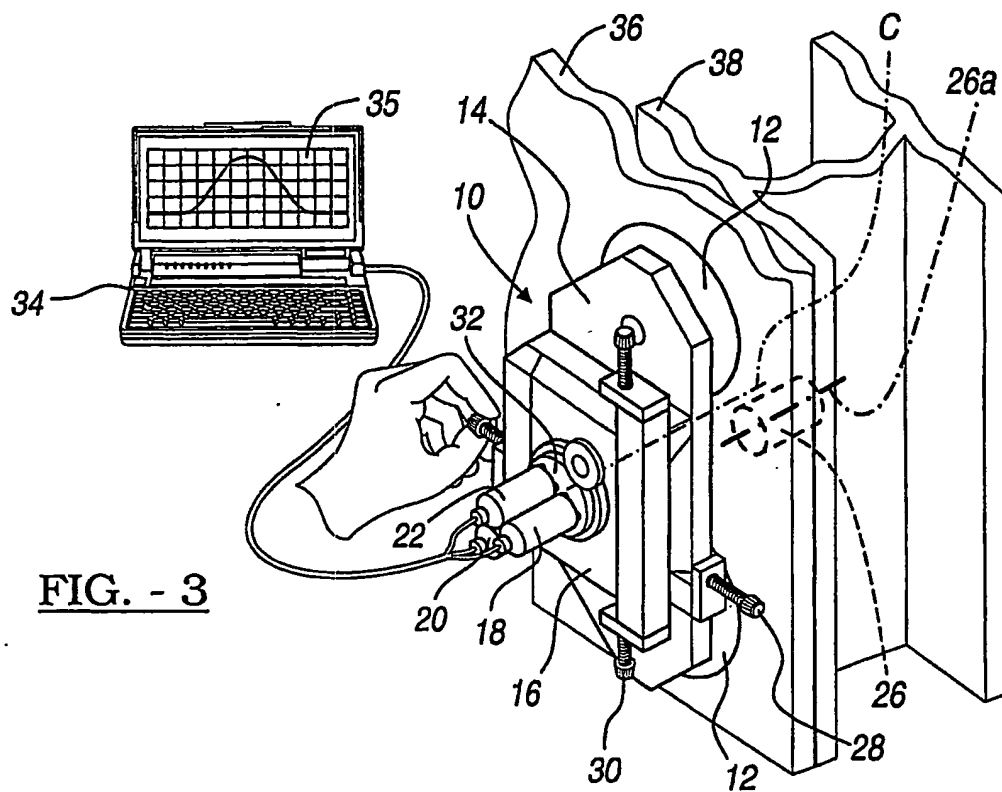
18. The method of claim 16, wherein providing a physical confirmation of said center field axis comprises providing a visual indication that said center probe axis, on said second side of said work piece, is substantially collinear with said center field axis on said first side of said work
5 piece.

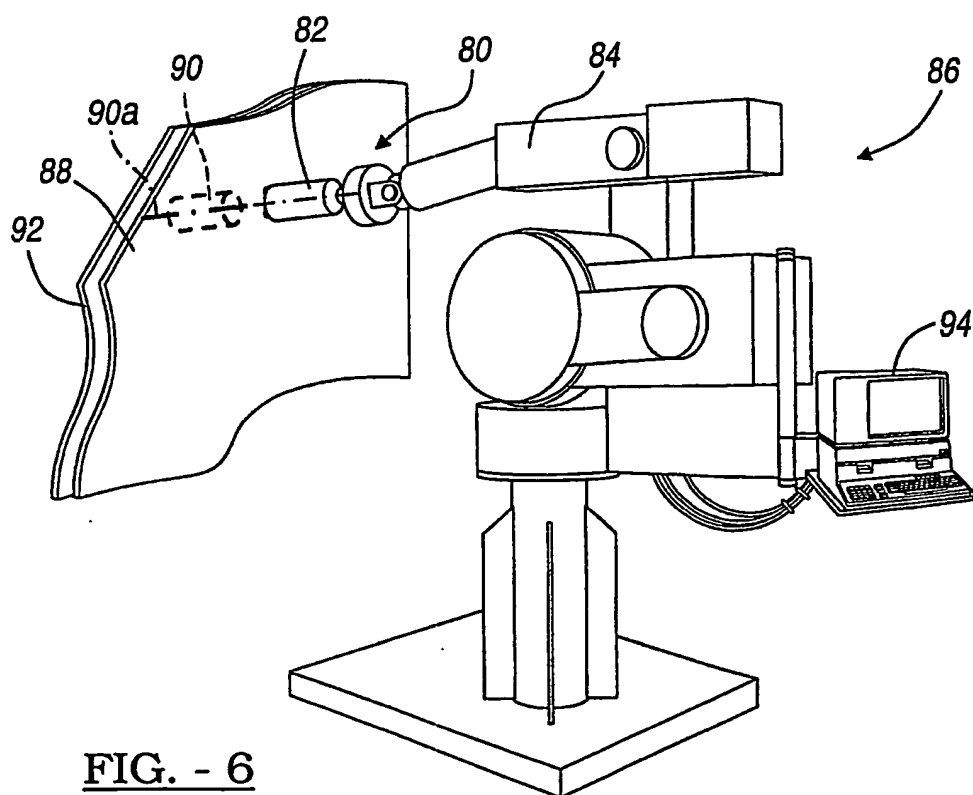
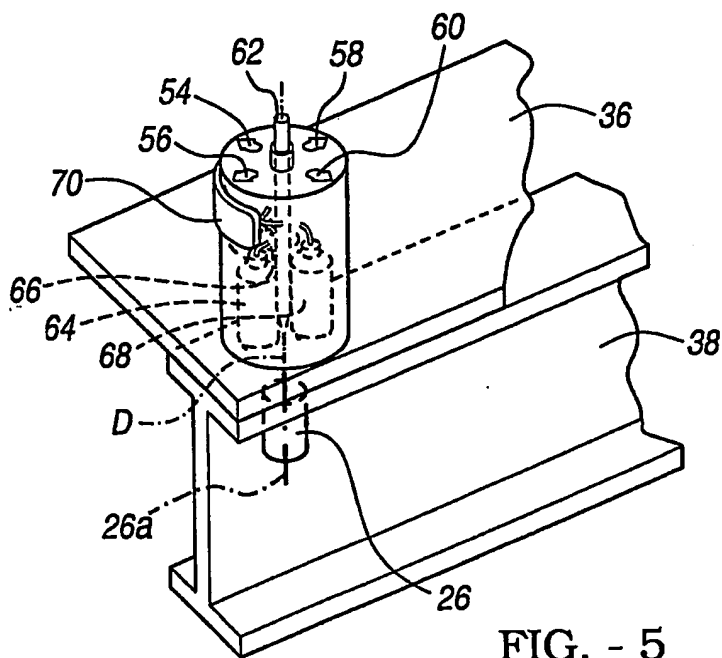
19. The method of claim 14, wherein providing a probe comprises:
providing a robot;
affixing a probe to said robot; and
10 controlling said robot such that said probe is placed near said second side of said work piece.

20. The method of claim 14, wherein in determining a center field axis comprises:
15 moving said probe relative to a point on said second side of said work piece;
affecting the probe with the field as the probe is moved over said work piece; and
providing a processor to determine the affect on said probe,
20 wherein said processor determines the center field axis.

21. The method of claim 14, wherein providing a physical confirmation of said center field axis comprises providing a visual indication that said center probe axis on said second side of said work piece is substantially collinear with said center field axis on said first side of said work
5 piece.







INTERNATIONAL SEARCH REPORT

International Application No.

PCT/US 03/13213

A. CLASSIFICATION OF SUBJECT MATTER

IPC 7 B25H1/00 B23B49/00 G01V3/08

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

IPC 7 B25H B23B G01V

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the International search (name of data base and, where practical, search terms used)

EPO-Internal, PAJ, WPI Data

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	GB 2 363 432 A (STEELE LESLIE) 19 December 2001 (2001-12-19) column 1, line 41 - line 44 column 1, line 46 - line 48 column 4, line 55 - line 58 column 6, line 35 - line 44 column 7, line 13 - line 15 column 7, line 19 - line 28 figures 1,5,8	1-7, 9-18,20
Y	---	8,19
X	US 5 434 500 A (HAUCK BRUCE ET AL) 18 July 1995 (1995-07-18) page 2, paragraph 2 - paragraph 3 figures 1-3 --- -/-	1-7, 9-18,20

☒ Further documents are listed in the continuation of box C.☒ Patent family members are listed in annex.

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"&" document member of the same patent family

Date of the actual completion of the International search

10 July 2003

Date of mailing of the International search report

18/07/2003

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INTERNATIONAL SEARCH REPORT

International Application No

PCT/US 03/13213

C.(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	US 2002/050043 A1 (LOGAN TRENT ET AL) 2 May 2002 (2002-05-02) column 2, line 38 - line 45 figure 2 -----	8,19

INTERNATIONAL SEARCH REPORT

Information on patent family members

International Application No

PCT/US 03/13213

Patent document cited in search report		Publication date	Patent family member(s)	Publication date
GB 2363432	A	19-12-2001	NONE	
US 5434500	A	18-07-1995	NONE	
US 2002050043	A1	02-05-2002	US 6357101 B1 EP 1132164 A2	19-03-2002 12-09-2001

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